

What is claimed is:

1. A plating method, comprising:

5 disposing a substrate and an anode in such a state that the substrate faces said anode;

flowing a current between the substrate and said anode while supplying a plating liquid therebetween; and

10 moving a portion of the substrate facing said anode in such a state that an inner central portion of the surface of the substrate faces said anode for a longer time than an outer peripheral portion of the surface of the substrate faces said anode.

2. The plating method according to claim 1, wherein the portion of the substrate facing said anode is moved by rotation of the substrate.

15 3. The plating method according to claim 1, wherein the portion of the substrate facing said anode is moved by rotation of said anode.

4. The plating method according to claim 1, wherein the portion of the substrate facing said anode is moved by translation of said anode.